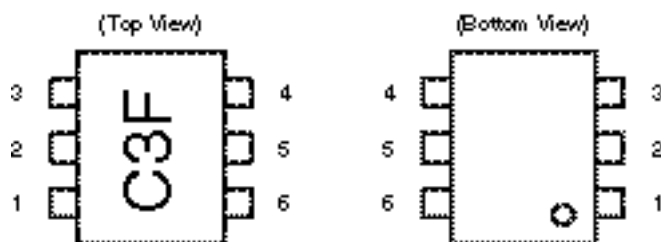


## PIN CONNECTIONS



Pin No.	Pin Name
1	INPUT
2	GND
3	GND
4	OUTPUT
5	GND
6	V <sub>CC</sub>

PRODUCT LINE-UP ( $T_A = +25^\circ\text{C}$ ,  $V_{CC} = V_{out} = 3.0\text{ V}$ ,  $Z_S = Z_L = 50\ \Omega$ )

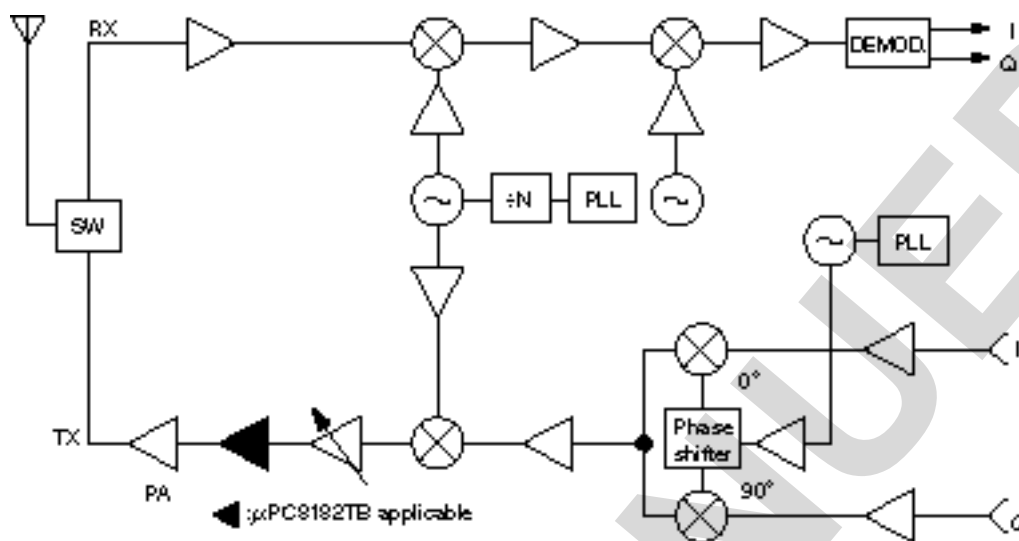
Part No.	$f_u$ (GHz)	P <sub>O</sub> (1 dB) (dBm)	G <sub>P</sub> (dB)	I <sub>CC</sub> (mA)	Package	Marking
$\mu$ PC8182TB	2.9	+9.5 @ $f = 0.9\text{ GHz}$ +9.0 @ $f = 1.9\text{ GHz}$ +8.0 @ $f = 2.4\text{ GHz}$	21.5 @ $f = 0.9\text{ GHz}$ 20.5 @ $f = 1.9\text{ GHz}$ 20.5 @ $f = 2.4\text{ GHz}$	30.0	6-pin super minimold	C3F
$\mu$ PC2762T	2.9	+8.0 @ $f = 0.9\text{ GHz}$	13.0 @ $f = 0.9\text{ GHz}$	26.5	6-pin minimold	C1Z
$\mu$ PC2762TB		+7.0 @ $f = 1.9\text{ GHz}$	15.5 @ $f = 1.9\text{ GHz}$		6-pin super minimold	
$\mu$ PC2763T	2.7	+9.5 @ $f = 0.9\text{ GHz}$	20.0 @ $f = 0.9\text{ GHz}$	27.0	6-pin minimold	C2A
$\mu$ PC2763TB		+6.5 @ $f = 1.9\text{ GHz}$	21.0 @ $f = 1.9\text{ GHz}$		6-pin super minimold	
$\mu$ PC2771T	2.2	+11.5 @ $f = 0.9\text{ GHz}$	21.0 @ $f = 0.9\text{ GHz}$	36.0	6-pin minimold	C2H
$\mu$ PC2771TB		+9.5 @ $f = 1.5\text{ GHz}$	21.0 @ $f = 1.5\text{ GHz}$		6-pin super minimold	
$\mu$ PC8181TB	4.0	+8.0 @ $f = 0.9\text{ GHz}$ +7.0 @ $f = 1.9\text{ GHz}$ +7.0 @ $f = 2.4\text{ GHz}$	19.0 @ $f = 0.9\text{ GHz}$ 21.0 @ $f = 1.9\text{ GHz}$ 22.0 @ $f = 2.4\text{ GHz}$	23.0	6-pin super minimold	C3E

**Remark** Typical performance. Please refer to ELECTRICAL CHARACTERISTICS in detail.

**Caution** The package size distinguishes between minimold and super minimold.

# SYSTEM APPLICATION EXAMPLE

## Digital cellular telephone



**Caution** The insertion point is different due to the specifications of conjunct devices.

## PIN EXPLANATION

Pin No.	Pin Name	Applied Voltage (V)	Pin Voltage (V) <small>Note</small>	Function and Applications	Internal Equivalent Circuit
1	INPUT	–	0.99	Signal input pin. A internal matching circuit, configured with resistors, enables 50 $\Omega$ connection over a wide band. A multi-feedback circuit is designed to cancel the deviations of $h_{FE}$ and resistance. This pin must be coupled to signal source with capacitor for DC cut.	
4	OUTPUT	Voltage as same as $V_{CC}$ through external inductor	–	Signal output pin. The inductor must be attached between $V_{CC}$ and output pins to supply current to the internal output transistors.	
6	$V_{CC}$	2.7 to 3.3	–	Power supply pin, which biases the internal input transistor. This pin should be externally equipped with bypass capacitor to minimize its impedance.	
2 3 5	GND	0	–	Ground pin. This pin should be connected to system ground with minimum inductance. Ground pattern on the board should be formed as wide as possible. All the ground pins must be connected together with wide ground pattern to decrease impedance difference.	

**Note** Pin voltage is measured at  $V_{CC} = 3.0$  V.

**ABSOLUTE MAXIMUM RATINGS**

Parameter	Symbol	Test Conditions	Ratings	Unit
Supply Voltage	V <sub>CC</sub>	T <sub>A</sub> = +25°C, pin 4 and pin 6	3.6	V
Total Circuit Current	I <sub>CC</sub>	T <sub>A</sub> = +25°C	60	mA
Power Dissipation	P <sub>D</sub>	T <sub>A</sub> = +85°C <b>Note</b>	270	mW
Operating Ambient Temperature	T <sub>A</sub>		–40 to +85	°C
Storage Temperature	T <sub>stg</sub>		–55 to +150	°C
Input Power	P <sub>in</sub>	T <sub>A</sub> = +25°C	+10	dBm

**Note** Mounted on double-sided copper-clad 50 × 50 × 1.6 mm epoxy glass PWB

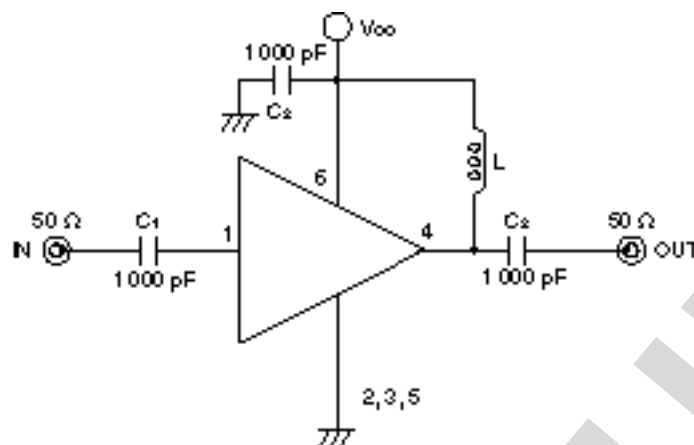
**RECOMMENDED OPERATING RANGE**

Parameter	Symbol	MIN.	TYP.	MAX.	Unit	Remarks
Supply Voltage	V <sub>CC</sub>	2.7	3.0	3.3	V	Same voltage should be applied to pin 4 and pin 6.
Operating Ambient Temperature	T <sub>A</sub>	–40	+25	+85	°C	–

**ELECTRICAL CHARACTERISTICS****( $T_A = +25^\circ\text{C}$ ,  $V_{CC} = V_{out} = 3.0\text{ V}$ ,  $Z_S = Z_L = 50\ \Omega$ , unless otherwise specified)**

Parameter	Symbol	Test Conditions	MIN.	TYP.	MAX.	Unit
Circuit Current	$I_{CC}$	No signal	–	30.0	38.0	mA
Power Gain	$G_P$	$f = 0.9\text{ GHz}$	19.0	21.5	25.0	dB
		$f = 1.9\text{ GHz}$	18.0	20.5	24.0	
		$f = 2.4\text{ GHz}$	18.0	20.5	24.0	
Noise Figure	NF	$f = 0.9\text{ GHz}$	–	4.5	6.0	dB
		$f = 1.9\text{ GHz}$	–	4.5	6.0	
		$f = 2.4\text{ GHz}$	–	5.0	6.5	
Upper Limit Operating Frequency	$f_u$	3 dB down below from gain at $f = 0.1\text{ GHz}$	2.6	2.9	–	GHz
Isolation	ISL	$f = 0.9\text{ GHz}$	28	33	–	dB
		$f = 1.9\text{ GHz}$	27	32	–	
		$f = 2.4\text{ GHz}$	26	31	–	
Input Return Loss	$RL_{in}$	$f = 0.9\text{ GHz}$	5	8	–	dB
		$f = 1.9\text{ GHz}$	7	10	–	
		$f = 2.4\text{ GHz}$	9	12	–	
Output Return Loss	$RL_{out}$	$f = 0.9\text{ GHz}$	7	10	–	dB
		$f = 1.9\text{ GHz}$	8	11	–	
		$f = 2.4\text{ GHz}$	11	14	–	
Gain 1 dB Compression Output Power	$P_{O(1dB)}$	$f = 0.9\text{ GHz}$	+7.0	+9.5	–	dBm
		$f = 1.9\text{ GHz}$	+6.5	+9.0	–	
		$f = 2.4\text{ GHz}$	+5.5	+8.0	–	
Saturated Output Power	$P_{O(sat)}$	$f = 0.9\text{ GHz}$ , $P_{in} = -5\text{ dBm}$	–	+11.0	–	dBm
		$f = 1.9\text{ GHz}$ , $P_{in} = -5\text{ dBm}$	–	+10.5	–	
		$f = 2.4\text{ GHz}$ , $P_{in} = -5\text{ dBm}$	–	+10.0	–	

## TEST CIRCUITS

COMPONENTS OF TEST CIRCUIT  
FOR MEASURING ELECTRICAL  
CHARACTERISTICS

	Type	Value
C <sub>1</sub> , C <sub>2</sub>	Bias Tee	1 000 pF
C <sub>3</sub>	Capacitor	1 000 pF
L	Bias Tee	1 000 nH

## EXAMPLE OF ACTUAL APPLICATION COMPONENTS

	Type	Value	Operating Frequency
C <sub>1</sub> to C <sub>3</sub>	Chip capacitor	1 000 pF	100 MHz or higher
L	Chip inductor	100 nH	100 MHz or higher
		10 nH	2.0 GHz or higher

## INDUCTOR FOR THE OUTPUT PIN

The internal output transistor of this IC consumes 20 mA, to output medium power. To supply current for output transistor, connect an inductor between the Vcc pin (pin 6) and output pin (pin 4). Select large value inductance, as listed above.

The inductor has both DC and AC effects. In terms of DC, the inductor biases the output transistor with minimum voltage drop to output enable high level. In terms of AC, the inductor makes output-port-impedance higher to get enough gain. In this case, large inductance and Q is suitable.

For above reason, select an inductance of 100 Ω or over impedance in the operating frequency. The gain is a peak in the operating frequency band, and suppressed at lower frequencies.

The recommendable inductance can be chosen from example of actual application components list as shown above.

## CAPACITORS FOR THE VCC, INPUT, AND OUTPUT PINS

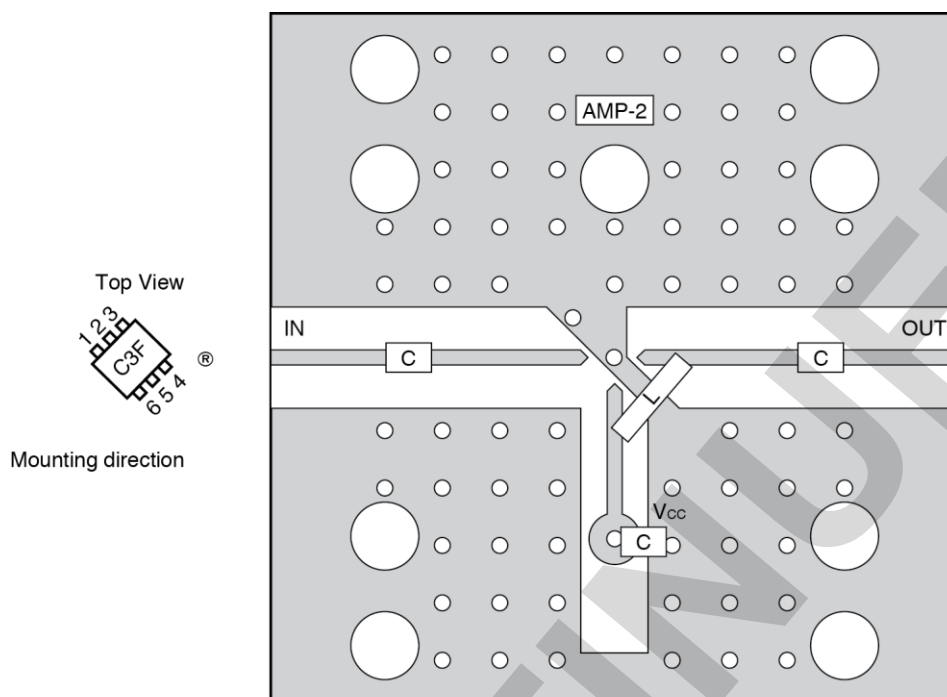
Capacitors of 1 000 pF are recommendable as the bypass capacitor for the Vcc pin and the coupling capacitors for the input and output pins.

The bypass capacitor connected to the Vcc pin is used to minimize ground impedance of Vcc pin. So, stable bias can be supplied against Vcc fluctuation.

The coupling capacitors, connected to the input and output pins, are used to cut the DC and minimize RF serial impedance. Their capacitance are therefore selected as lower impedance against a 50 Ω load. The capacitors thus perform as high pass filters, suppressing low frequencies to DC.

To obtain a flat gain from 100 MHz upwards, 1 000 pF capacitors are used in the test circuit. In the case of under 10 MHz operation, increase the value of coupling capacitor such as 10 000 pF. Because the coupling capacitors are determined by equation,  $C = 1/(2\pi Rf_c)$ .

## ILLUSTRATION OF THE TEST CIRCUIT ASSEMBLED ON EVALUATION BOARD



## COMPONENT LIST

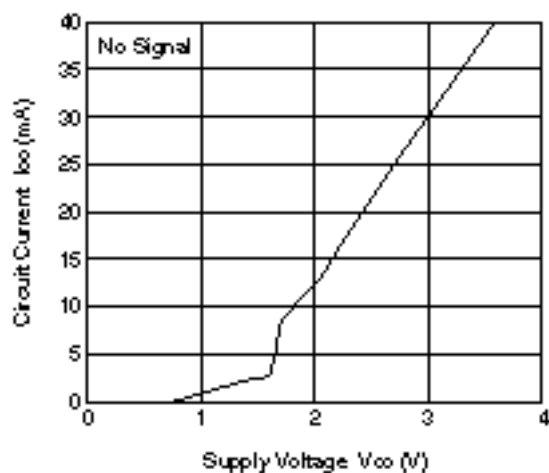
	Value
C	1 000 pF
L	Example: 10 nH

## Notes

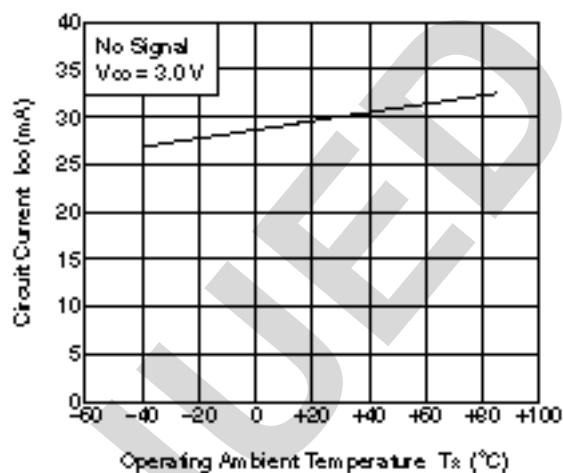
1. 30 × 30 × 0.4 mm double-sided copper-clad polyimide board.
2. Back side: GND pattern
3. Solder plated on pattern
4. ○ ○ : Through holes

TYPICAL CHARACTERISTICS ( $T_A = +25^\circ\text{C}$ , unless otherwise specified)

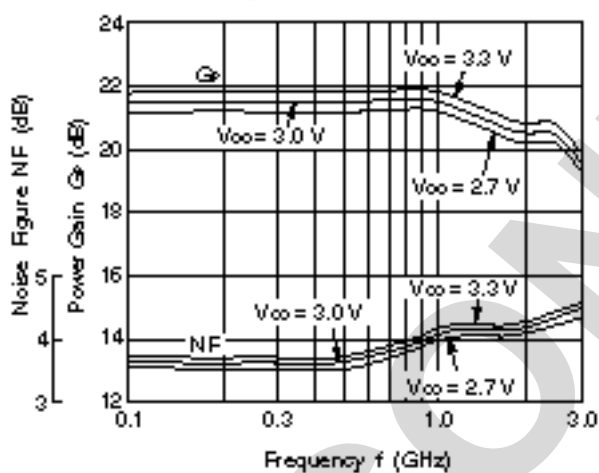
CIRCUIT CURRENT vs. SUPPLY VOLTAGE



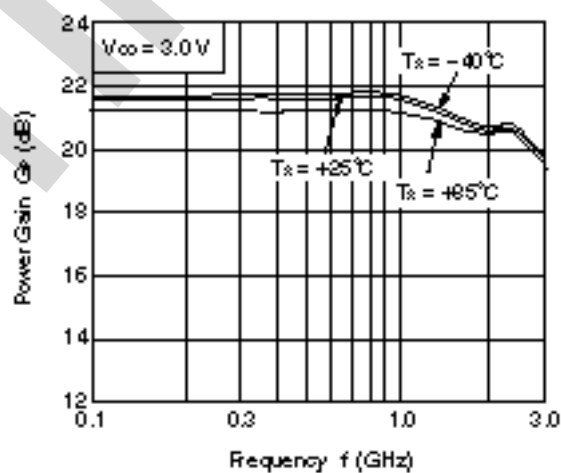
CIRCUIT CURRENT vs. OPERATING AMBIENT TEMPERATURE



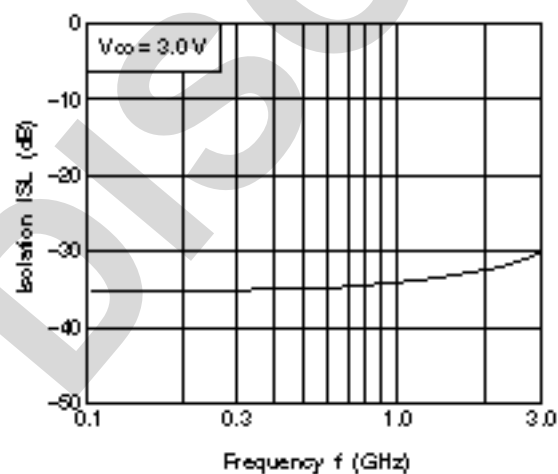
NOISE FIGURE, POWER GAIN vs. FREQUENCY



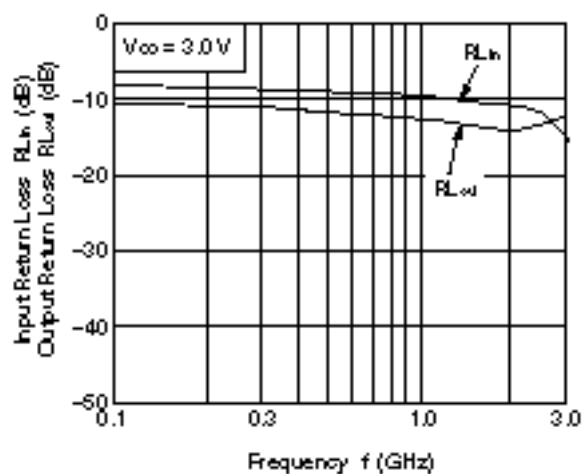
POWER GAIN vs. FREQUENCY



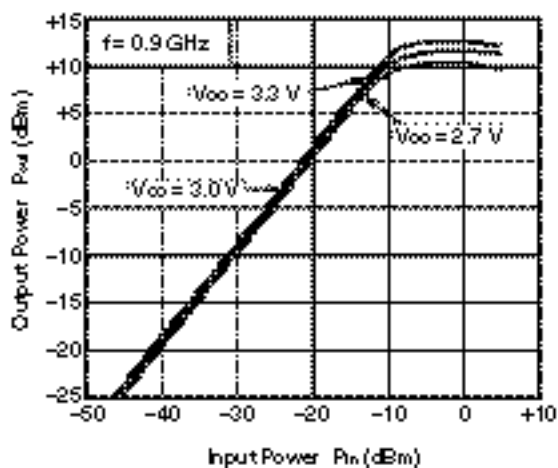
ISOLATION vs. FREQUENCY



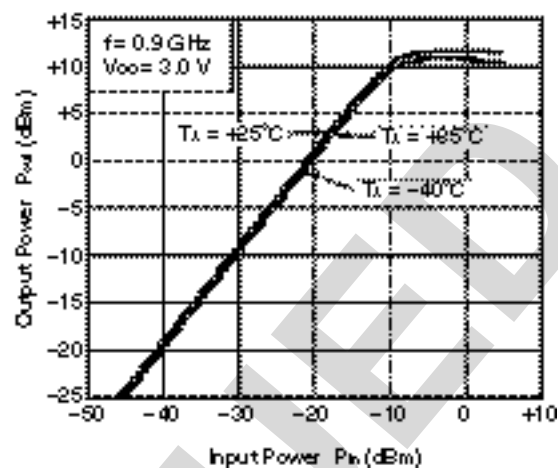
INPUT RETURN LOSS, OUTPUT RETURN LOSS vs. FREQUENCY



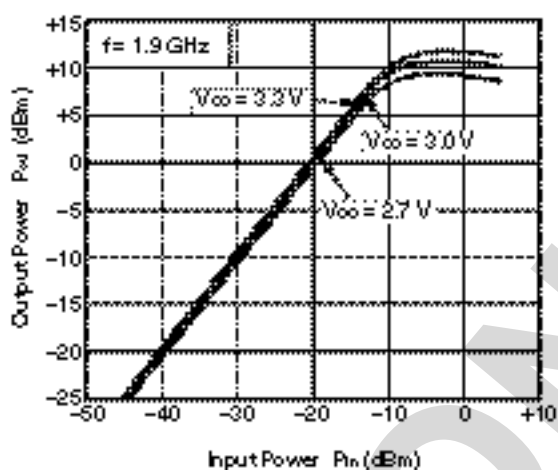
OUTPUT POWER vs. INPUT POWER



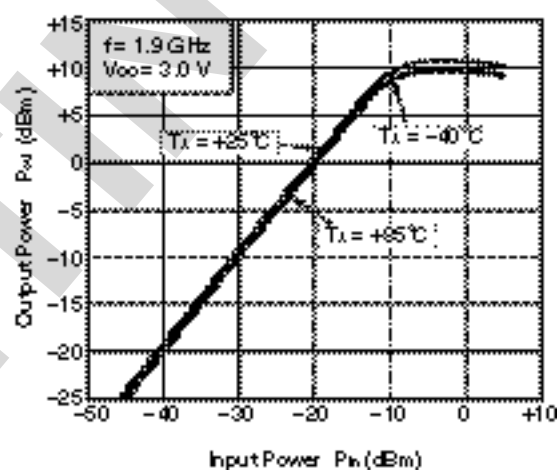
OUTPUT POWER vs. INPUT POWER



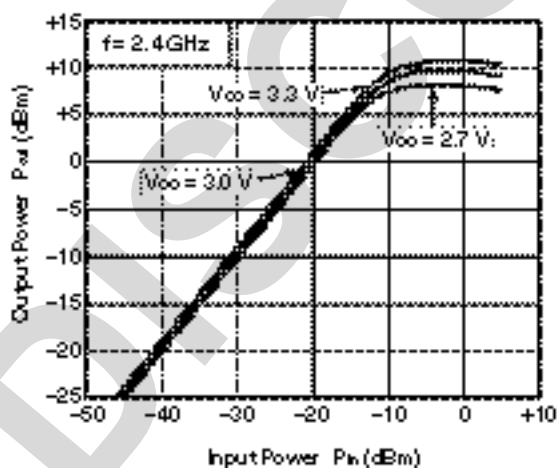
OUTPUT POWER vs. INPUT POWER



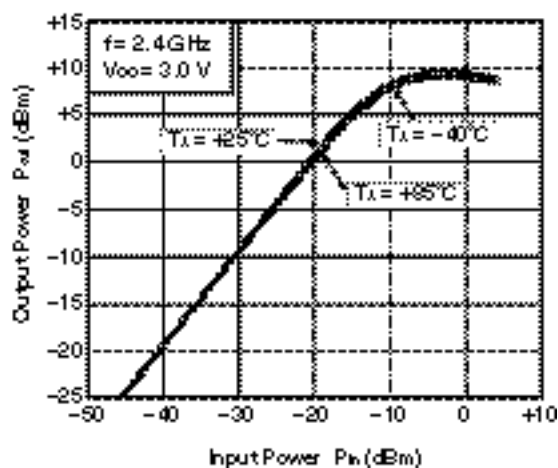
OUTPUT POWER vs. INPUT POWER



OUTPUT POWER vs. INPUT POWER

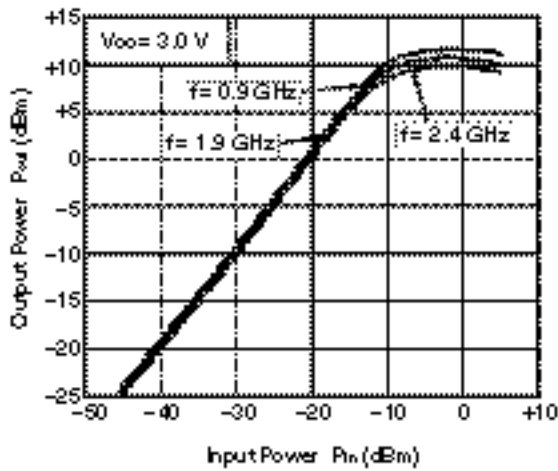


OUTPUT POWER vs. INPUT POWER

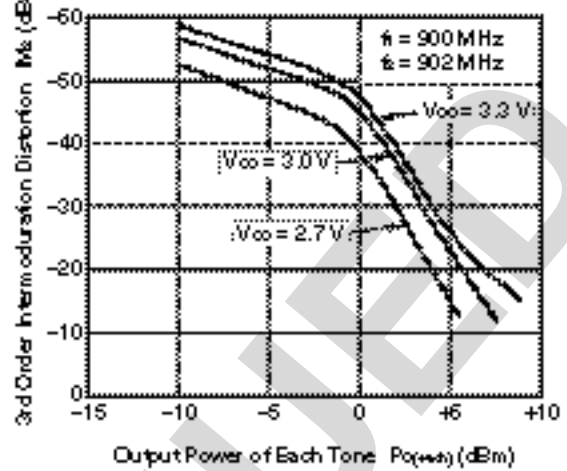




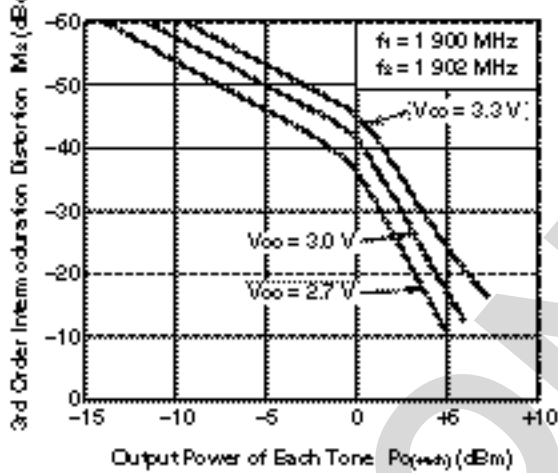
OUTPUT POWER vs. INPUT POWER



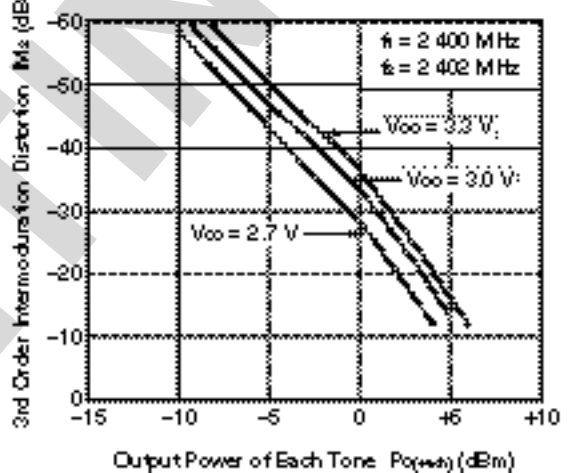
3RD ORDER INTERMODULATION DISTORTION vs. OUTPUT POWER OF EACH TONE



3RD ORDER INTERMODULATION DISTORTION vs. OUTPUT POWER OF EACH TONE



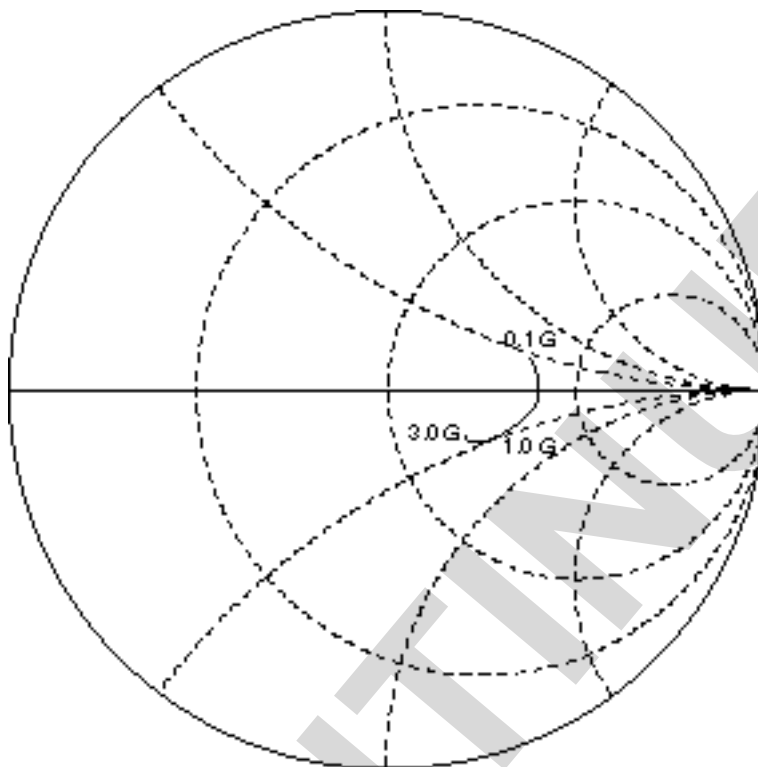
3RD ORDER INTERMODULATION DISTORTION vs. OUTPUT POWER OF EACH TONE



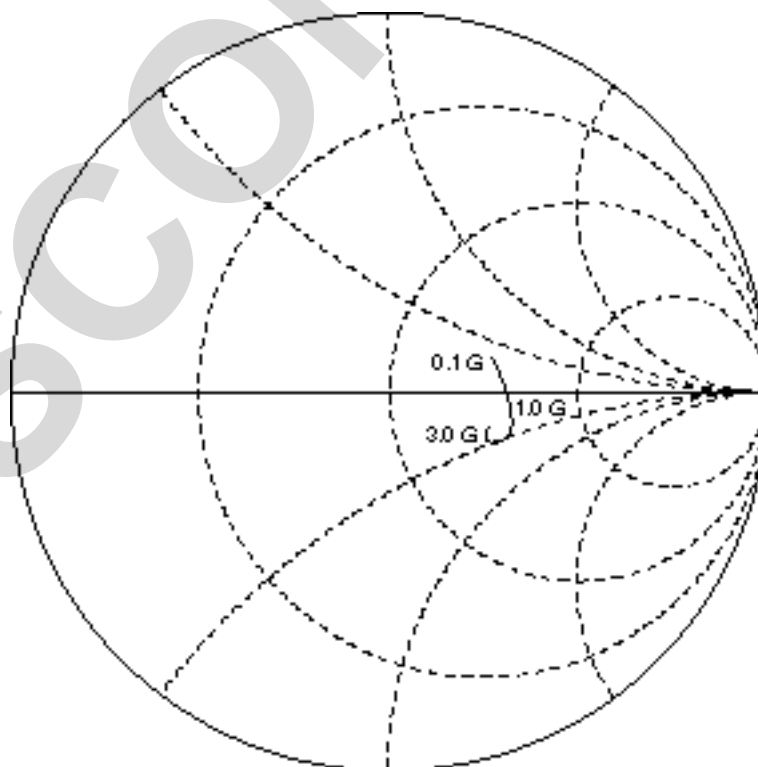
**Remark** The graphs indicate nominal characteristics.

**SMITH CHART ( $V_{CC} = V_{out} = 3.0\text{ V}$ )**

S<sub>11</sub>-FREQUENCY



S<sub>22</sub>-FREQUENCY



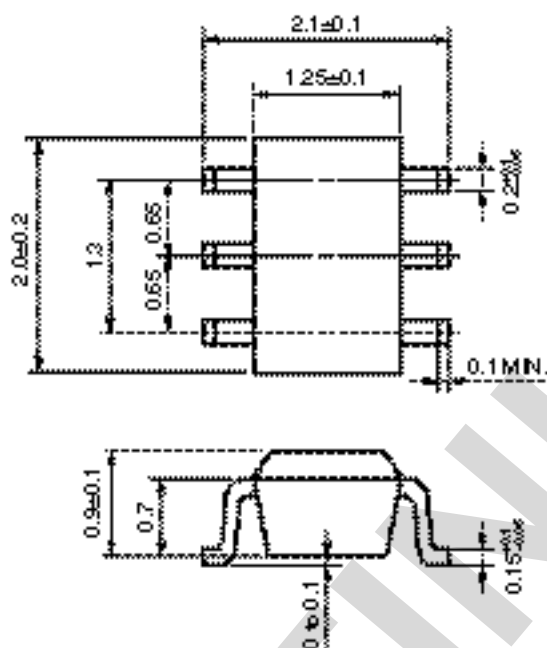
**★ S-PARAMETERS**

- S-parameters and noise parameters are provided on our Web site in a format (S2P) that enables the direct import of the parameters to microwave circuit simulators without the need for keyboard inputs.
- Click here to download S-parameters.
- [RF and Microwave] ® [Device Parameters]
- URL <http://www.necel.com/microwave/en/>

DISCONTINUED

## PACKAGE DIMENSIONS

6-PIN SUPER MINIMOLD (UNIT: mm)



**NOTES ON CORRECT USE**

- (1) Observe precautions for handling because of electro-static sensitive devices.
- (2) Form a ground pattern as widely as possible to minimize ground impedance (to prevent undesired oscillation).  
All the ground pins must be connected together with wide ground pattern to decrease impedance difference.
- (3) The bypass capacitor should be attached to the V<sub>cc</sub> pin.
- (4) The inductor must be attached between V<sub>cc</sub> and output pins. The inductance value should be determined in accordance with desired frequency.
- (5) The DC cut capacitor must be attached to input and output pin.

**RECOMMENDED SOLDERING CONDITIONS**

This product should be soldered and mounted under the following recommended conditions. For soldering methods and conditions other than those recommended below, contact your nearby sales office.

Soldering Method	Soldering Conditions	Condition Symbol
Infrared Reflow	Peak temperature (package surface temperature) : 260°C or below Time at peak temperature : 10 seconds or less Time at temperature of 220°C or higher : 60 seconds or less Preheating time at 120 to 180°C : 120±30 seconds Maximum number of reflow processes : 3 times Maximum chlorine content of rosin flux (% mass) : 0.2%(Wt.) or below	IR260
VPS	Peak temperature (package surface temperature) : 215°C or below Time at temperature of 200°C or higher : 25 to 40 seconds Preheating time at 120 to 150°C : 30 to 60 seconds Maximum number of reflow processes : 3 times Maximum chlorine content of rosin flux (% mass) : 0.2%(Wt.) or below	VP215
Wave Soldering	Peak temperature (molten solder temperature) : 260°C or below Time at peak temperature : 10 seconds or less Preheating temperature (package surface temperature) : 120°C or below Maximum number of flow processes : 1 time Maximum chlorine content of rosin flux (% mass) : 0.2%(Wt.) or below	WS260
Partial Heating	Peak temperature (pin temperature) : 350°C or below Soldering time (per side of device) : 3 seconds or less Maximum chlorine content of rosin flux (% mass) : 0.2%(Wt.) or below	HS350

**Caution** Do not use different soldering methods together (except for partial heating).